



## EtraLED-LG-8580 LG Innotek Modular Passive Star Heat Sink Ф85mm

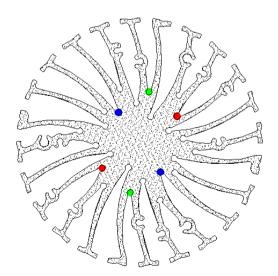
#### **Features VS Benefits**

- The EtraLED-LG-8580 LG Innotek Modular Passive Star LED Heat Sinks are specifically designed luminaires using the LG Innotek LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 2000 to 5,100 lumen.
- \* Thermal resistance range Rth 1.47°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of LG Innotek COB series.
- \* Diameter 85.0mm standard height 80.0mm Other heights on request.
- \* Forged from highly conductive aluminum.

#### Zhaga LED engine and radiator assembly is a unified future international standardization

- \* Below you find an overview of LG Innotek COB's and LED modules which standard fit on the srar LED heat sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.





#### LG Innotek LED Modules directly Mounting Options LG Innotek 7W&10W COB series.

LEMWM19490xxxxxx

With the Zhaga Book 3 holders for the green indicator marks.

Without the holders for the blue indicator marks.

Direct mounting with machine screws M3x6.5mm

#### LG Innotek 16W&21W COB series.

With the Zhaga Book 3 holders for the green indicator marks.

Direct mounting with machine screws M3x6.5mm.





## **Mounting Options and Drawings & Dimensions**

Example:EtraLED-LG-8580-B-1,2

Example:EtraLED-LG-85 1

kampie:EtraLED-LG-85

1 Height (mm)

**Anodising Color** 

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

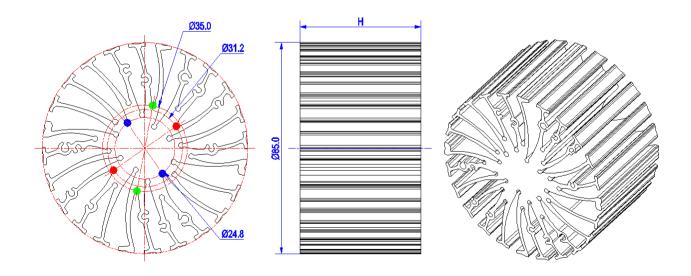
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means option 1 and 2 combined

#### **Notes:**

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	7W&10W COB	/	М3	6.5mm	24.8mm/ 2-@180°
2		/	М3	6.5mm	31.2mm/ 2-@180°
3	16W&21W COB	BJB Holder 47.319.2011.50	МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
		TE Holder 2213130-1			
	7W&10W COB	TE Holder 2213382-1			



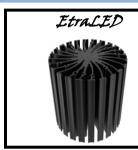




# EtraLED

### EtraLED-LG-8580 LG Innotek Modular Passive Star Heat Sink Ф85mm

#### The product deta table

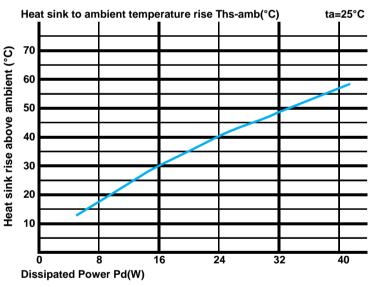


Model No.	EtraLED-LG-8580
Heatsink Size	Ф85хH80mm
Heatsink Material	AL6063-T5
Finish	Black Anodized
Weight (g)	458.0
Dissipated power (Ths-amb,50℃)	34.0 (W)
Cooling surface area (mm²)	148458
Thermal Resistance (Rhs-amb)	1.47 (°C/W)

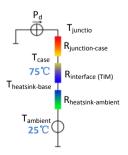
#### The thermal data table

- \* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- \*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (I \eta L)$ .
  - Pd Dissipated power ; Pe Electrical power ;  $\eta L =$  Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		EtraLED-LG-8580		
Dissipated Power Pd(W)	8.0	2.25	18.0	
	16.0	1.88	30.0	
	24.0	1.67	40.0	
	32.0	1.50	48.0	
	40.0	1.40	56.0	



- \*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:module} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$
- $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.1-0.15 mm\ is\ recommended.$



- \*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths Ta)/Pd$
- $\theta$  Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- \*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{junction-case}$ , the thermal resistance of the TIM outside the package is  $R_{interface}(TIM)$  ["C,M"], the thermal resistance with the heat sink is  $R_{heatsink-ambient}$  ["C,M"], and the ambient temperature is  $T_{ambient}$  ["C].
- \*Thermal resistances outside the package  $R_{interface}$  (TIM) and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:  $T_{iunction} = (R_{unction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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